

Conference Programme Day 1, Thursday February 14

08:00-08:30	Conference Registration and Table Top & Poster Exhibition build up	Table Top & Poster Display Area
08:30-08:45	Welcome by the EIPC President	Alun Morgan, EIPC, UK
Keynote Session 1: New Business & Technology Roadmap for different market segments		Moderator: Alun Morgan, EIPC, UK
08:45-09:15	Business Outlook: Global Electronics Industry	Walt Custer, Custer Consulting, US
09:15-09:45	PCB Trends for Manufacturing- from Smartphone to Automotive	Erkko Helminen, TTM, FI
09:45-10:00	Panel discussion	
Session 2: New trends for Imaging of PCB's, Conductor & Solder Mask		Moderator: Tarja Rapala-Virtanen, EIPC, FI
10:00-10:20	Dry film for Automotive and New Exposure units Technology	Giorgio Favini, Elga Europe, IT
10:20-10:40	Orbotech Diamond TM10 - Solder Mask at its best	Uwe Altmann, Orbotech, BE
10:40-11:00	The Importance of Reduction in Metal etching for Today's and Future PCB Designs	Hironori Takashima, MEC Europe, BE
11:00-11:30	30 minutes Coffee break	Table Top & Poster Display Area
11:30-11:50	Comparative Analysis of Multiple Laser Sources for Cutting/Ablation Efficacy and Quality on HDI PCB and ICP Materials	Christopher Ryder, ESI, US
11:50-12:10	Recent developments with the Inkjet Soldermask	Don Monn, Taiyo America, US
12:10-12:30	PCB Automation - Green Manufacturing	TBA, Atotech, DE
12:30-12:50	Panel discussion	
12:50-14:00	Network Lunch	Hotel restaurant
Session 3: New advanced Materials for future Electronics		Moderator: Emma Hudson, Gen3 Systems, UK
14:00-14:20	Thermal Management	Alun Morgan, Ventec Europe, UK
14:20-14:40	LCP for hermetically sealed sensing applications	Sven Johannsen, Dyconex, CH
14:40-15:00	Radar High Frequency	Roland Schönholz, Technolam, DE
15:00-15:20	Specifying PCB Materials for HSD and microwave/millimeter wave product performance	Mike Miller, ITEQ, TW
15:20-15:40	Panel discussion	
16:00-19:00	Departure & Visit Factory Elga Europe	
19:30	Network Dinner Milan Centre	
22:30	Departure to NH Hotel Milano Fiera	

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Conference Programme Day 2, Friday February 15

Session 4: Cost effective Supply Chain management and Traceability		Moderator: Michele Stampanoni, Cicor Group, CH
09:00-09:20	To be announced	Nikola Kontic, Zuken, UK
09:20-09:40	Tested PCB Quality. The impact on Supply Chain management, Final PCBA yield and Profitability	Roland Valentini, Gardien Group, DE
09:40-10:00	To be announced	Markku Jämsä, Aspocomp, FI
10:00-10:10	Panel discussion	
Session 5: New soldering Technology, Quality assurance and Durability testing		Moderator: John Fix, Taiyo America, US
10:10-10:30	The current state of the Solder Limits	Emma Hudson, Gen3 Systems, UK
10:30-10:50	CT scanning and tomographic imaging technology for failure analysis	Robert Boguski, Datest, US
10:50-11:10	Development of High Reliability No Clean Solder Paste	Dr. Lei Wang, Heraeus Deutschland, DE
11:10-11:40	30 minutes Coffee break	Table Top & Poster Display Area
11:40-12:00	Principles of Silver sintering and importance of PCB finish	Michiel de Monchy, MacDermid-Alpha, DE
12:00-12:20	New automated controlled impedance tester	Hermann Reischer, Polar Instruments, AT
12:20-12:40	Panel discussion	
12:40-12:50	President closing remarks - End of Conference Day 2	
12:50-14:00	Network Lunch	Hotel restaurant

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